BROADCOM

PCN-CCX-001751

Product Change Notice

Issue Date: January 23, 2020

Change Type:

Add Assembly Production Site – Amkor China

Parts Affected:

BCM5727B0KFBG

Description and Extent of Change:

Add Amkor China as the assembly supplier for the above device

Reasons for Change:

Current assembly factory (StatsChipPAC Singapore) is discontinuing the ASSEMBLY ARRAY and PLASTIC LEADED manufacturing operation

Effect of Change on Fit, Form, Function, Quality, or Reliability:

There will be no change in fit, form, function, quality or reliability

Effective Date of Change:

May 31, 2020

Qualification Data:

Package Qualification Reference#:	3655.0001, 3655.0002, 3655.0003
Fab Technology:	40nm
Package Type:	DR-QFN

Package Size: 10x10mm
Lead Count: 196
Wire Bond Composition COPPER: 99.95% Cu/Pd-plated
Mold Compound KE-G1250LKDS_CU_WIRE

Stress Test	Condition	Read points	Sample Size	Requirements	Results (# fail/ss)
		Cycles / Hrs.			
Precondition	MSL3 JESD22-A113E		260 units	0 failures	0 / 260
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	77 units	0 failures	0 / 77
Thermal Shock	-55°C / 125°C JEDEC Std. 22-A106	300 cycles	77 units	0 failures	0 / 77
uHast	130°C/85%RH JEDEC Std. 22-A102-C	96hrs	77 units	0 failures	0 / 77
HTSL	TA=150°C	1000hrs	77 units	0 failures	0 / 77

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.